

Key performance:

- $V_{CE}=1200V$
- $I_C=200A@T_C=100^{\circ}C$
- $V_{CE(sat)}=1.7 V$

**Features:**

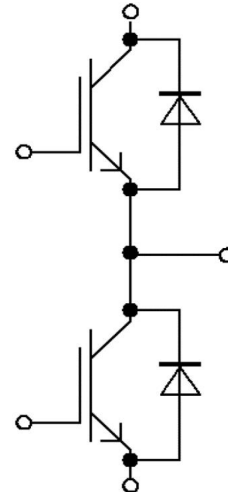
- Low V_{CEsat} .
- Low switching losses.
- Low stray inductance design.
- Positive V_{CEsat} temperature coefficient.

Benefits:

- High efficiency for application.
- Excellent current sharing in parallel operation.
- RoHS compliant.

Applications:

- Welding machines
- High frequency switching converters



Maximum rated values , IGBT

Parameter	Conditions	Symbol	Values	Unit
Collector-emitter voltage	$T_{vj} = 25^{\circ}\text{C}$	V_{CES}	1200	V
Continuous collector current	$T_C = 100^{\circ}\text{C}, T_{vj\text{ max}} = 175^{\circ}\text{C}$	I_C	200	A
Repetitive peak collector current	$t_p = 1\text{ ms}$	I_{CRM}	400	A
Total power dissipation	$T_C = 25^{\circ}\text{C}, T_{vj\text{ max}} = 175^{\circ}\text{C}$	P_{tot}	1150	W
Gate-emitter peak voltage		V_{GES}	± 20	V

Characteristic values , IGBT

Parameter	Conditions	Symbol	Values			Unit
			Min.	Typ.	Max.	
Collector-emitter saturation voltage	$I_C = 200\text{A}, V_{GE} = 15\text{ V}$ $T_{vj} = 25^{\circ}\text{C}$	V_{CESat}	-	1.7	-	V
Gate threshold voltage	$I_C = 1.5\text{ mA}, V_{CE} = V_{GE}$ $T_{vj} = 25^{\circ}\text{C}$	V_{GEth}	-	5.7	-	V
Gate charge	$V_{GE} = -15 / 15\text{ V}$	Q_G	-	1.85	-	μC
Input capacitance	$f = 1\text{ MHz}, T_{vj} = 25^{\circ}\text{C},$ $V_{CE} = 25\text{ V}, V_{GE} = 0\text{ V}$	C_{ies}	-	15.2	-	nF
Reverse transfer capacitance		C_{res}	-	0.65	-	nF
Collector-emitter leakage current	$V_{CE} = 1200\text{ V}, V_{GE} = 0\text{ V},$ $T_{vj} = 25^{\circ}\text{C}$	I_{CES}	-	-	1.0	mA
Gate-emitter leakage current	$V_{CE} = 0\text{ V}, V_{GE} = 20\text{ V},$ $T_{vj} = 25^{\circ}\text{C}$	I_{GES}	-	-	100	nA
Turn-on delay time, inductive load	$I_C = 200\text{A}, V_{CE} = 600\text{ V}$ $V_{GE} = -15 / 15\text{ V} ,$ $R_G = 4.5\Omega$ $T_{vj} = 25^{\circ}\text{C}$	$t_{d(on)}$	-	155	-	ns
Rise time, inductive load		t_r	-	90	-	ns
Turn-off delay time, inductive load		$t_{d(off)}$	-	330	-	ns
Fall time, inductive load		t_f	-	95	-	ns
Turn-on energy loss per pulse		E_{on}	-	11	-	mJ
Turn-off energy loss per pulse		E_{off}	-	10	-	mJ
Thermal resistance, junction to case		per IGBT	R_{thJC}	-	-	0.13
Thermal resistance, case to heatsink	per IGBT	R_{thCH}	-	0.04	-	K/W
Temperature under switching conditions		$T_{vj\text{ op}}$	-40	-	150	$^{\circ}\text{C}$

Maximum rated values , Diode

Parameter	Conditions	Symbol	Values	Unit
Repetitive peak reverse voltage	$T_{vj} = 25^{\circ}\text{C}$	V_{RRM}	1200	V
Continuous DC forward current		I_F	200	A
Repetitive peak forward current	$t_p = 1 \text{ ms}$	I_{FRM}	400	A

Characteristic values , Diode

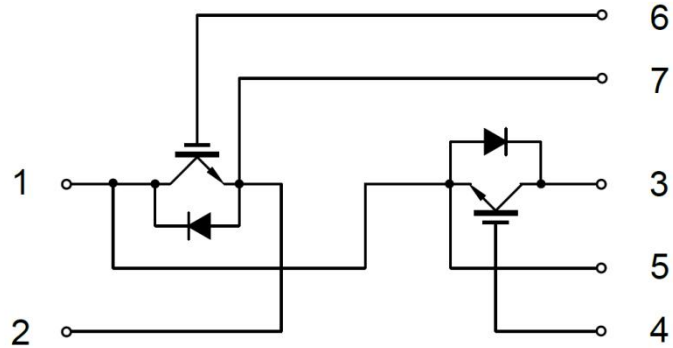
Parameter	Conditions	Symbol	Values			Unit
			Min.	Typ.	Max.	
Forward voltage	$I_F = 200\text{A}, V_{GE} = 0 \text{ V}$ $T_{vj} = 25^{\circ}\text{C}$	V_F	-	2.0	-	V
Peak reverse recovery current	$I_F = 200 \text{ A}, -d_{iF}/d_t = 1800 \text{ A}/\mu\text{s}$	I_{RR}	-	50	-	A
Recovered charge	$V_R = 600 \text{ V}, V_{GE} = -15 \text{ V}$ $R_G = 4.5\Omega$	Q_{RR}	-	16	-	μC
Reverse recovery energy	$T_{vj} = 25^{\circ}\text{C}$	E_{rec}	-	2.6	-	mJ
Thermal resistance, junction to case	per diode	R_{thJC}	-	-	0.2	K/W
Thermal resistance, case to heatsink	per diode	R_{thCH}	-	0.05	-	K/W
Temperature under switching conditions		$T_{vj op}$	-40	-	150	$^{\circ}\text{C}$

Module characteristic values

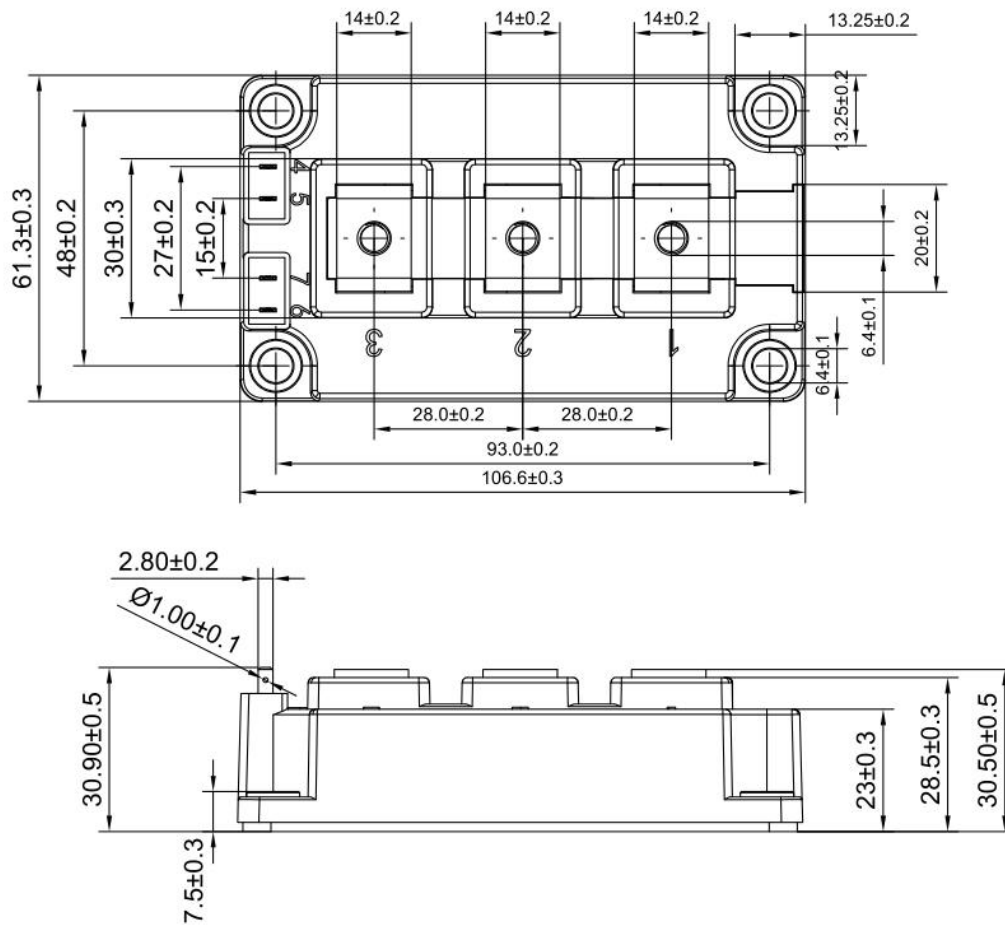
Parameter	Conditions	Symbol	Values	Unit
Isolation test voltage	RMS, f = 50 Hz, t = 1 min.	V_{ISOL}	2.5	kV
Internal isolation	basic insulation (class 1, IEC 61140)		Al_2O_3	
Creepage distance	terminal to heatsink		29	mm
	terminal to terminal		23	
Clearance	terminal to heatsink		23	mm
	terminal to terminal		21	
Comperative tracking index		CTI	> 400	

Parameter	Conditions	Symbol	Values			Unit
			Min.	Typ.	Max.	
Stray inductance module		L_{sCE}	-	20	-	nH
Module lead resistance, terminals - chip	$T_C = 25^\circ C$, per switch	$R_{CC+EE'}$	-	0.7	-	m Ω
Storage temperature		T_{stg}	-40	-	125	$^\circ C$
Mounting torque	Screw:M6	M	3	-	6	Nm
Weight		G	-	345	-	g

Circuit diagram



Package outlines (mm)



Revision history

Date	Revision	Changes
Jan 11, 2025	Rev 1.0	Release of the preliminary datasheet.

Disclaimer

PLEASE NOTE - Jiangsu JieJie Microelectronics Co., Ltd ("JJM") reserves the right to amend, correct, modify and enhance the product and/or this document at any time without prior notice. If you intend to purchase this product, please obtain the latest information available before placing your order. The sale of JJM products is governed by JJM's prevailing terms and conditions at the time of purchase and purchasers are solely responsible for the selection and use of the products with no liability on JJM's part to supply application assistance or customization. Purchase of JJM products does not grant the purchaser license, express or implied, to JJM's intellectual property. Any warranties provided with JJM products are null and void upon resale unless accompanied by the information set forth herein in its entirety. The JJM name and logo are registered trademarks of Jiangsu JieJie Microelectronics Co., Ltd. This document supersedes all previous versions. ©2025 JJM - All rights reserved